

From: David Jordan, Reg. No. 50,325
To: Examiner C. Lam
Interview Agenda, Application No. 10/022,503
Monday, August 4, 2003, 1:00 pm

Interview Agenda

This is to confirm that we have scheduled a personal interview for Monday, August 4, 2003, at 1:00 p.m. to discuss Application No. 10/022,503. As agreed upon, I have prepared the following proposed agenda.

In our discussion, I intend to discuss how the features of O'Keefe are different from those of the invention, particularly with regard to the connection state maintaining means, which maintains a connection portion between the surface of each of the lands to which the wiring pattern is connected and the wiring pattern in a state not wetted by solder and for maintaining the printed wiring board, except for the connection portion, in a state wetted by solder.

Furthermore, I have attached the following proposed claim amendment:

PROPOSED CLAIM SHEET FOR INTERVIEW
DO NOT ENTER

1. (Currently Amended) A printed wiring board comprising:
a substrate having two opposite surfaces and a plurality of soldering through holes formed in said substrate;
wherein each of said plurality of soldering through holes opens in said opposite surfaces for inserting leads of an inserted component to be mounted onto the printed wiring board and soldering said leads of an inserted component onto said substrate,
wherein each of said plurality of soldering through holes has an inner peripheral surface and a pair of lands each formed continuously across said opposite surfaces therewith and
~~the inner peripheral surface of a corresponding each of said plurality of soldering through holes,~~
wherein at least one land of said pair of lands is connected to at least one wiring pattern;
said printed wiring board further comprising:
connection state maintaining means for maintaining a connection portion between the surface of each of said lands to which said wiring pattern is connected and said wiring pattern in a state not wetted by solder and for maintaining said printed wiring board, except for said connection portion, in a state wetted by solder.

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